L Number	Hits	Search Text	DB	Time stamp
239	1	((semiconductor rs mi\$1conductor) n ar3	USPAT;	2003/06/18
	. •	dynamic) with (adhesive near3 film)	US-P PUB	15:04
	28	((semiconductor or semi\$1conductor) n ar3	USPAT:	2003/06/18
241	20	, · · ·		15:10
	4=	dynamic) and (adhesive near3 film)	US-P PUB	
242	17	(dynamic near3 (sensor or detector)) and	USPAT;	2003/06/18
	_	(adhesive near3 film)	US-PGPUB	15:30
243	7	(sensor near3 chip) with (adhesive near3	USPAT;	2003/06/18
		film)	US-PGPUB	15:56
244	7	("5266827"   "5656711"   "5747694"	USPAT	2003/06/18
		"6034421"   "6040400"   "6121359"		15:32
		"6127504").PN.		
249	2	(sensor near3 chip) near5 (adhesive near3	USPAT;	2003/06/18
		film) near4 (substrate )	US-PGPUB	16:00
250	2	(sensor near3 chip) with ((adhesive near3	USPAT;	2003/06/18
	_	film) or (polymide near3 resin)) near4	US-PGPUB	16:01
		(substrate )		
251 255	5	(sensor near3 chip) with ((adhesive near3	EPO; JPO;	2003/06/18
	•	film) or (polymide near3 resin))	DERWENT	16:25
	9	((sensor near3 chip) near3 (coupl\$3 or	USPAT;	2003/06/18
233	•	attach\$3 or connect\$4 or laminat\$3 or	US-PGPUB	16:41
		mount\$3 ) near3 ((circuit near chip) or	00-10100	10.41
	4-	substrate)) and (adhesive near3 film)	HCDAT.	2003/06/18
256	47	((sensor near3 chip) same ((circuit near3	USPAT;	
		chip) or substrate)) and ((adhesive near3	US-PGPUB	17:12
		film) or (polymide near3 resin))		0000/00/40
257	4652	((circuit near3 chip) or substrate) with	USPAT;	2003/06/18
į		((adhesive near3 film) or (polymide near3	US-PGPUB	17:14
		resin))		
258	937	(((circuit near3 chip) or substrate) near4	USPAT;	2003/06/18
		(mount\$3 on attach\$3 or connect\$ or	US-PGPUB	17:19
		interpose\$3 or laminat\$3)) with ((adhesive		
		near3 film) or (polymide near3 resin))		
260	1	(((circuit near3 chip) or substrate) with	USPAT;	2003/06/18
į		((adhesive near3 film) or (polymide near3	US-PGPUB	17:22
ĺ		resin))) same (dynamic near3 sensor)		
259	8	(((circuit near3 chip) or substrate) with	USPAT;	2003/06/18
		((adhesive near3 film) or (polymide near3	US-PGPUB	17:22
		resin))) same (acceleration)		
261	2	((((circuit near3 chip) or substrate) near4	USPAT;	2003/06/18
20.	_	(mount\$3 on attach\$3 or connect\$ or	US-PGPUB	17:23
		interpose\$3 or laminat\$3)) with ((adhesive		
		near3 film) or (polymide near3 resin))) same		
		1		
	_	(acceleration)	HCDAT-	2002/06/46
262	2	((((circuit near3 chip) or substrate) near4	USPAT;	2003/06/18
		(mount\$3 on attach\$3 or connect\$ or	US-PGPUB	17:24
		interp se\$3 or laminat\$3)) with ((adhesive		
		near3 film) r (polymid near3 resin))) same		
		(sensor near3 chip)		

263	10	((sensor near3 chip) n ar3 (coupl\$3 or	USPAT;	2003/06/18
		attach\$3 or connect\$4 or laminat\$3 or	US-P PUB	17:28
		mount\$3 ) near3 ((circuit near3 chip) or		
		substrat )) and (adhesive near3 film)		
264	11	((sensor near3 chip) near3 (coupl\$3 or	USPAT;	2003/06/18
		attach\$3 or connect\$4 or laminat\$3 or	US-PGPUB	18:04
		mount\$3 ) near3 ((circuit near3 chip) or		
		substrate)) and ((adhesive near3 film) or		
		polyimide near3 adhesive)		
265	0	(stack\$3 near3 microchip) with ((adhesive	USPAT;	2003/06/18
		near3 film) or (polyimide near3 adhesive))	US-PGPUB	18:05
266	5	(stack\$3 near3 microchip) and ((adhesive	USPAT;	2003/06/18
		near3 film) or (polyimide near3 adhesive))	US-PGPUB	18:07
267	30	(stack\$3 near3 microchip) and ((adhesive	USPAT;	2003/06/18
		near3 film) or ((polyimide or polymer) near3	US-PGPUB	18:09
		(adhesive or fllm)))		